

### **Technical Data Sheet**

MODEL NO: S5060ANB4 5060 Package 5.0 X 5.0mm TOP LEDs

#### Features:

• Compatible with automatic placement equipment

• Compatible with reflow solder process

• Using InGaN blue chip

#### Applications:

Indicators

• Automotive: backlighting in dashboard and switch

Backlight for LCD

Dice material	Emitted color	Lens Color
InGaN	Blue	Water Clear

### Electrical/Optical Characteristics(Ta=25°C)

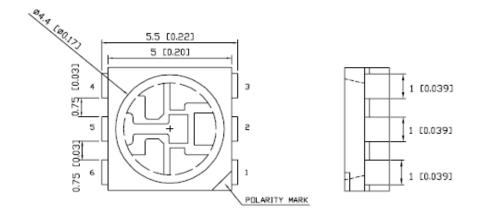
Parameter	Test	Symbol	Value			l lmit
	Condition		Min	Тур	Max	Unit
Wavelength at peak emission	If=60mA	λ peak		468		nm
Spectral half bandwidth	If=60mA	Δλ		30		nm
Dominant wavelength	If=60mA	λ dom	464		473	nm
Forward voltage	If=20mA	Vf	2.8		3.6	V
Luminous intensity	If=60mA	lv	845		1400	mcd
Viewing angle	If=10mA	2 <i>\theta</i> 1/2		120		Deg
Reverse current	Vr=5V	lr			10	μА

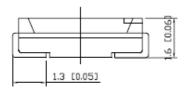
### Absolute Maximum Ratings(Ta=25°C)

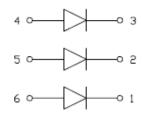
Parameter	Symbol	Value	Unit
Power dissipation	Pd	100	mW
Forward current	lf	25	mA
Reverse voltage	Vr	5	V
Operating temperature range	Тор	-40 ~+85	$^{\circ}\!\mathbb{C}$
Storage temperature range	Tstg -40 ~+85	-40 ~+85	$^{\circ}\!\mathbb{C}$
Peak pulsing current (1/8 duty f=1kHz)	Ifp	125	mA



## PACKAGING DIMENSIONS

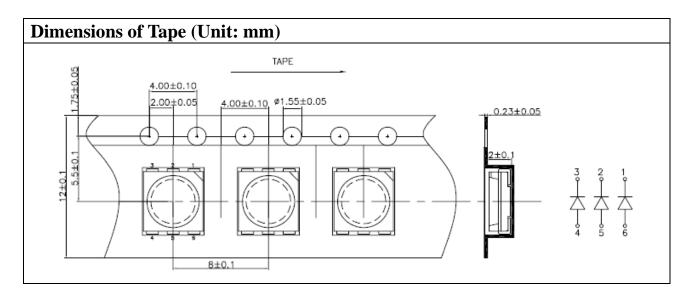


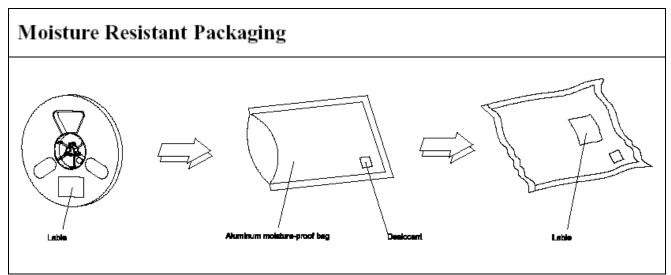






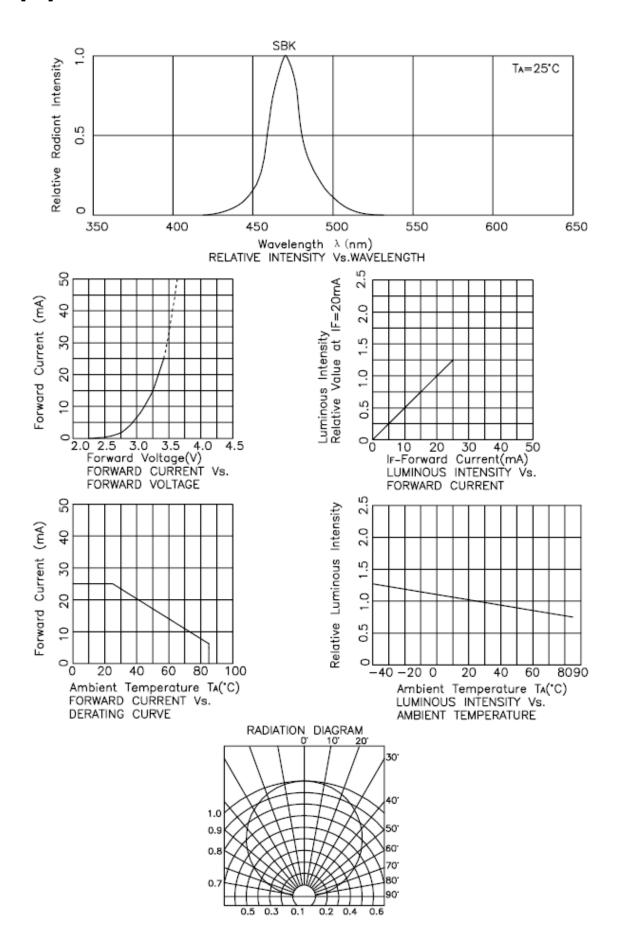
### PACKAGING SPECIFICATIONS





### NOTES

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. The polarity mark is oriented towards the tape sprocket hole;
- 4. 1,000pcs/Reel.





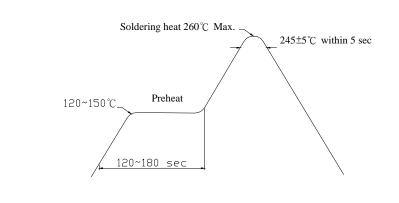
#### **Descriptions**:

The Chip-LED Taping is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.

Besides, lightweight makes them ideal for miniature application, etc.

### Soldering heat reliability (DIP):

Please refer to the following figure:



#### **Precautions For Use:**

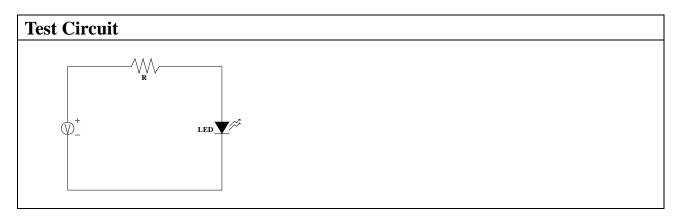
#### Over - current - proof

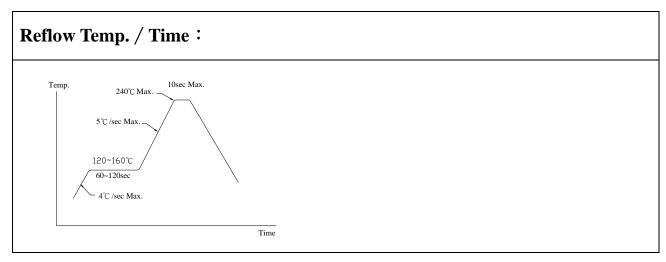
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

#### Storage

- 1. The operation of temperature and R.H. are :  $5^{\circ}$ C  $\sim 30^{\circ}$ C, 60%R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is :  $60^{\circ}\text{C}\pm5^{\circ}\text{C}$  for 15hrs.







<b>Reliability Test Items And Conditions</b>

The reliability of products shal be satisfied with items listed below.

No.	Items	Test Condition	Test	Sample
110.	items	Test Condition	Hours/Cycles	Size
1	Solder Heat	TEMP : 260°C ±5°C	5 sec	48 pcs
2	Temperature Cycle	90°C ~ 25°C ~ -30°C ~ 25 °C 30m 5m 30m 5m	300Cycles	48 Pcs
3	Thermal Shick	100°C ~ -55°C 10m 10m	100Cycles	48 Pcs
4	Operation Life	If=20mA	1000 Hrs	48 Pcs
5	High Temperature Storage	Temp:90°C	1000Hrs	48 Pcs
6	Low Temperature Storage	Temp:-30°C	1000Hrs	48 Pcs
7	High Temperature/High Humidity	80°C / R.H80%	1000Hrs	48 Pcs